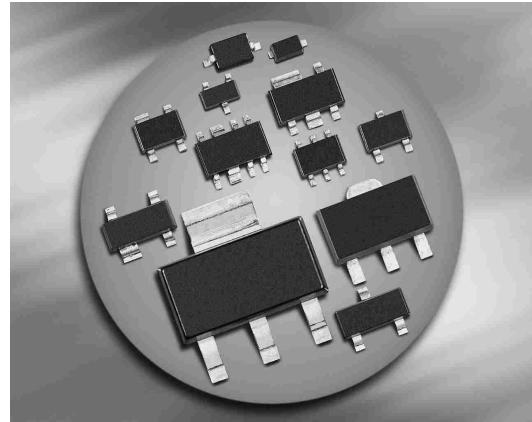


NPN Silicon AF Transistors

- For AF input stages and driver applications
- High current gain
- Low collector-emitter saturation voltage
- Low noise between 30 Hz and 15 kHz
- Complementary types:
BC856...-BC860...(PNP)
- Pb-free (RoHS compliant) package¹
- Qualified according AEC Q101



¹Pb-containing package may be available upon special request

Type	Marking	Pin Configuration						Package
BC846A	1As	1=B	2=E	3=C	-	-	-	SOT23
BC846B	1Bs	1=B	2=E	3=C	-	-	-	SOT23
BC846BW	1Bs	1=B	2=E	3=C	-	-	-	SOT323
BC847A	1Es	1=B	2=E	3=C	-	-	-	SOT23
BC847B	1Fs	1=B	2=E	3=C	-	-	-	SOT23
BC847BF*	1Fs	1=B	2=E	3=C	-	-	-	TSFP-3
BC847BL3	1F	1=B	2=E	3=C	-	-	-	TSLP-3-1
BC847BW	1Fs	1=B	2=E	3=C	-	-	-	SOT323
BC847C	1Gs	1=B	2=E	3=C	-	-	-	SOT23
BC847CW	1Gs	1=B	2=E	3=C	-	-	-	SOT323
BC848A	1Js	1=B	2=E	3=C	-	-	-	SOT23
BC848B	1Ks	1=B	2=E	3=C	-	-	-	SOT23
BC848BL3	1K	1=B	2=E	3=C	-	-	-	TSLP-3-1
BC848BW	1Ks	1=B	2=E	3=C	-	-	-	SOT323
BC848C	1Ls	1=B	2=E	3=C	-	-	-	SOT23
BC848CW	1Ls	1=B	2=E	3=C	-	-	-	SOT323
BC849B	2Bs	1=B	2=E	3=C	-	-	-	SOT23
BC849C	2Cs	1=B	2=E	3=C	-	-	-	SOT23
BC849CW	2Cs	1=B	2=E	3=C	-	-	-	SOT323
BC850B	2Fs	1=B	2=E	3=C	-	-	-	SOT23
BC850BW	2Fs	1=B	2=E	3=C	-	-	-	SOT323
BC850C	2Gs	1=B	2=E	3=C	-	-	-	SOT23
BC850CW	2Gs	1=B	2=E	3=C	-	-	-	SOT323

* Not for new design

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage BC846...	V_{CEO}	65	V
BC847..., BC850...		45	
BC848..., BC849...		30	
Collector-emitter voltage BC846...	V_{CES}	80	
BC847..., BC850...		50	
BC848..., BC849...		30	
Collector-base voltage BC846...	V_{CBO}	80	
BC847..., BC850...		50	
BC848..., BC849...		30	
Emitter-base voltage BC846...	V_{EBO}	6	
BC847..., BC850...		6	
BC848..., BC849...		6	
Collector current	I_C	100	mA
Peak collector current, $t_p \leq 10$ ms	I_{CM}	200	
Total power dissipation- $T_S \leq 71$ °C, BC846-BC850	P_{tot}	330	mW
$T_S \leq 128$ °C, BC847F		250	
$T_S \leq 135$ °C, BC847L3-BC848L3		250	
$T_S \leq 124$ °C, BC846W-BC850W		250	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BC846-BC850	R_{thJS}	≤ 240	K/W
BC847F		≤ 90	
BC847L3-BC848L3		≤ 60	
BC846W-BC850W		≤ 105	

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 10 \text{ mA}, I_B = 0$, BC846...	$V_{(\text{BR})\text{CEO}}$	65	-	-	V
$I_C = 10 \text{ mA}, I_B = 0$, BC847..., BC850...		45	-	-	
$I_C = 10 \text{ mA}, I_B = 0$, BC848..., BC849...		30	-	-	
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$, BC846...	$V_{(\text{BR})\text{CBO}}$	80	-	-	
$I_C = 10 \mu\text{A}, I_E = 0$, BC847..., BC850...		50	-	-	
$I_C = 10 \mu\text{A}, I_E = 0$, BC848..., BC849...		30	-	-	
Emitter-base breakdown voltage $I_E = 0, I_C = 10 \mu\text{A}$	$V_{(\text{BR})\text{EBO}}$	-	6	-	
Collector-base cutoff current $V_{CB} = 45 \text{ V}, I_E = 0$ $V_{CB} = 30 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$	I_{CBO}	-	0.015	-	μA
-		-	5	-	
DC current gain ¹⁾ $I_C = 10 \mu\text{A}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.A}$ $I_C = 10 \mu\text{A}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.B}$ $I_C = 10 \mu\text{A}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.C}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.A}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.B}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, h_{FE}\text{-grp.C}$	h_{FE}	-	140	-	-
-		-	250	-	
-		-	480	-	
-		110	180	220	
-		200	290	450	
-		420	520	800	
Collector-emitter saturation voltage ¹⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 5 \text{ mA}$	$V_{CE\text{sat}}$	-	90	250	mV
-		-	200	600	
Base emitter saturation voltage ¹⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 5 \text{ mA}$	$V_{BE\text{sat}}$	-	700	-	
-		-	900	-	
Base-emitter voltage ¹⁾ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}$	$V_{BE(\text{ON})}$	580	660	700	
-		-	-	770	

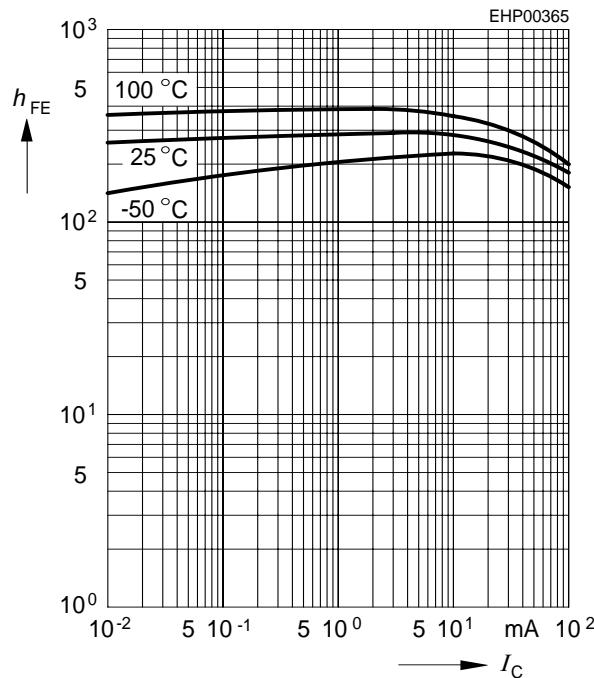
¹Pulse test: $t < 300\mu\text{s}$; $D < 2\%$

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	f_T	-	250	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	C_{cb}	-	0.95	-	pF
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}$	C_{eb}	-	9	-	
Short-circuit input impedance $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.A}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.B}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.C}$	h_{11e}	-	2.7	-	kΩ
Open-circuit reverse voltage transf. ratio $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.A}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.B}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.C}$	h_{12e}	-	1.5	-	10^{-4}
Short-circuit forward current transf. ratio $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.A}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.B}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.C}$	h_{21e}	-	200	-	
Open-circuit output admittance $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.A}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.B}$ $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz}, h_{FE}-\text{grp.C}$	h_{22e}	-	18	-	μS
Noise figure $I_C = 200 \mu\text{A}, V_{CE} = 5 \text{ V}, f = 1 \text{ kHz},$ $\Delta f = 200 \text{ Hz}, R_S = 2 \text{ kΩ}, \text{BC849...}, \text{BC850...}$	F	-	1.2	4	dB
Equivalent noise voltage $I_C = 200 \mu\text{A}, V_{CE} = 5 \text{ V}, R_S = 2 \text{ kΩ},$ $f = 10 \dots 50 \text{ Hz}, \text{BC850...}$	V_n	-	-	0.135	μV

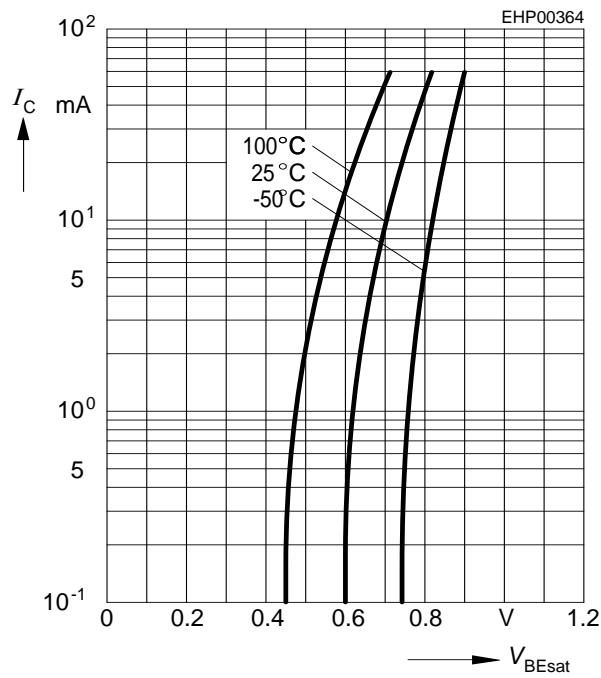
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5 \text{ V}$



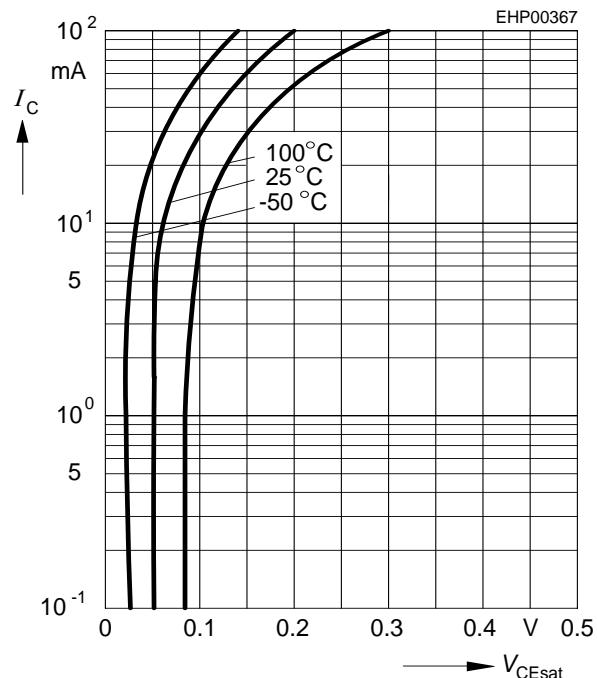
Base-emitter saturation voltage

$I_C = f(V_{BEsat}), h_{FE} = 20$



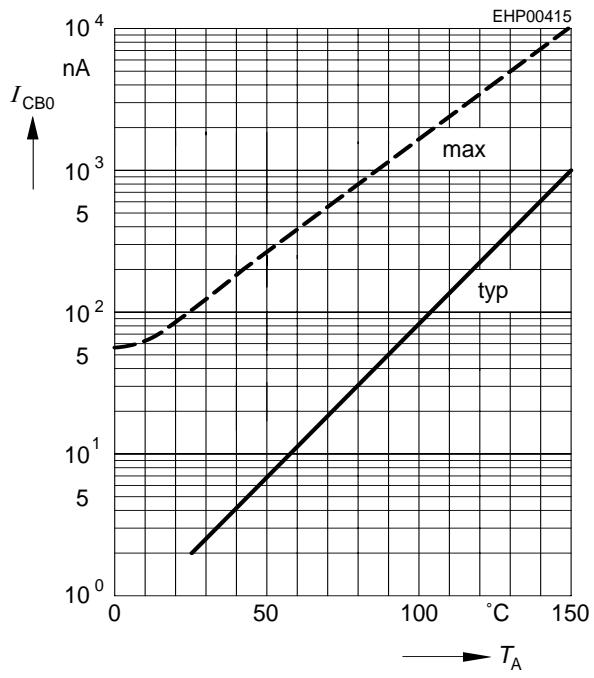
Collector-emitter saturation voltage

$I_C = f(V_{CEsat}), h_{FE} = 20$



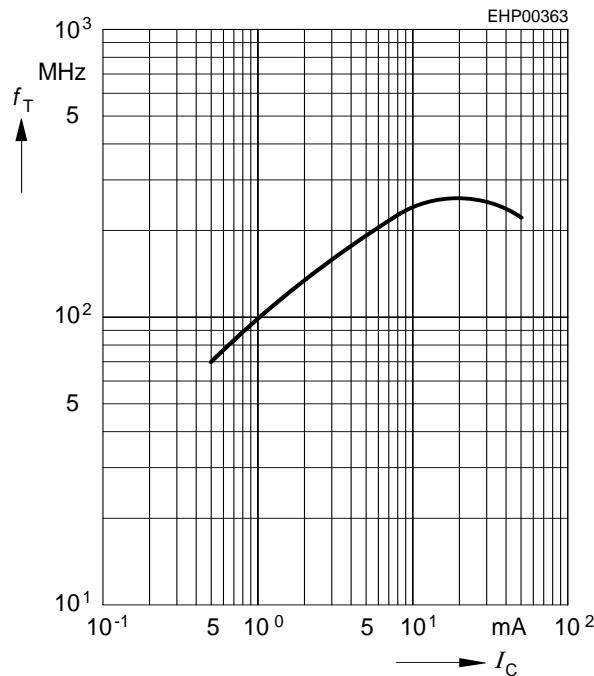
Collector cutoff current $I_{CBO} = f(T_A)$

$V_{CB} = 30 \text{ V}$



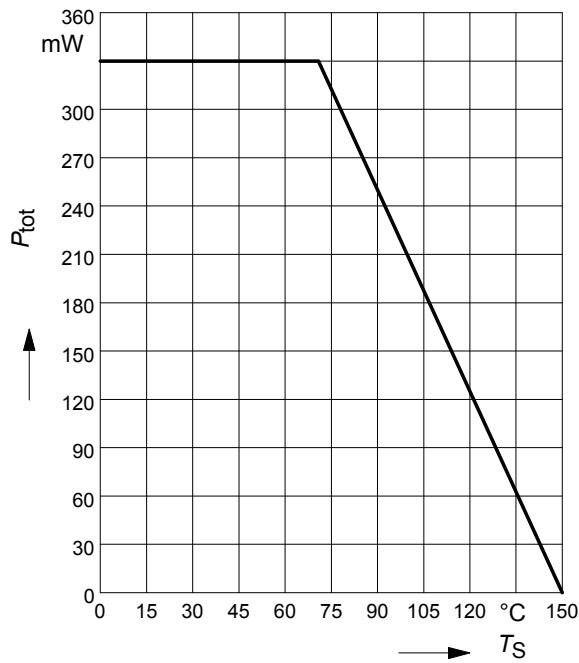
Transition frequency $f_T = f(I_C)$

$V_{CE} = 5 \text{ V}$



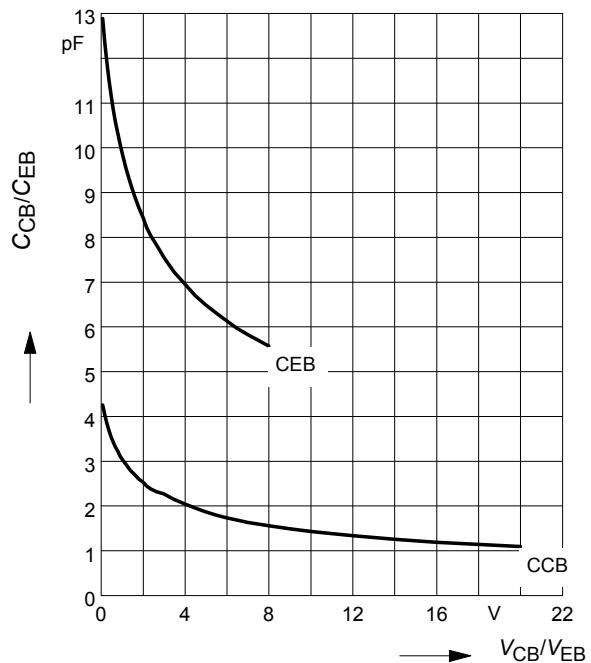
Total power dissipation $P_{tot} = f(T_S)$

BC846-BC850



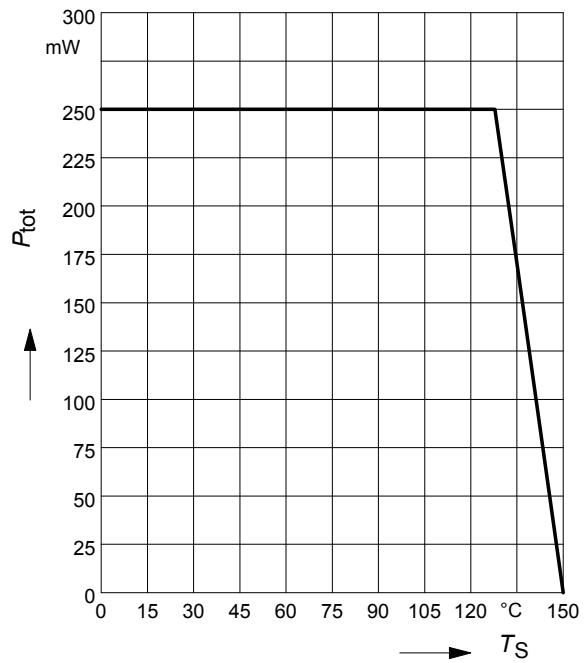
Collector-base capacitance $C_{cb} = f(V_{CB})$

Emitter-base capacitance $C_{eb} = f(V_{EB})$

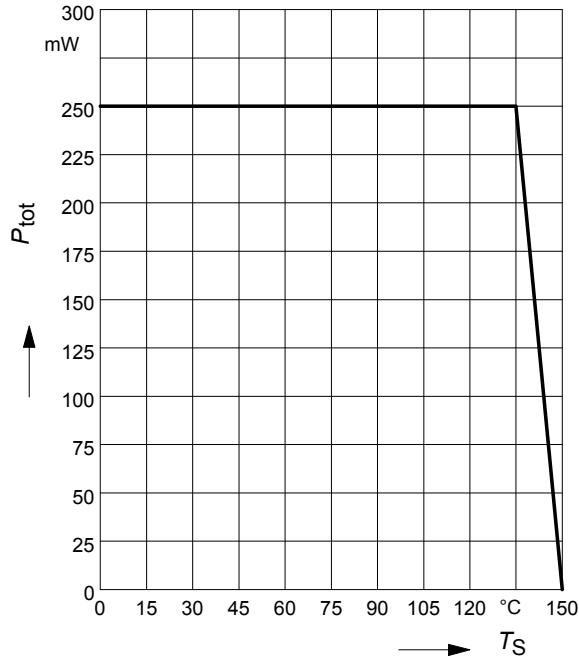


Total power dissipation $P_{tot} = f(T_S)$

BC847BF

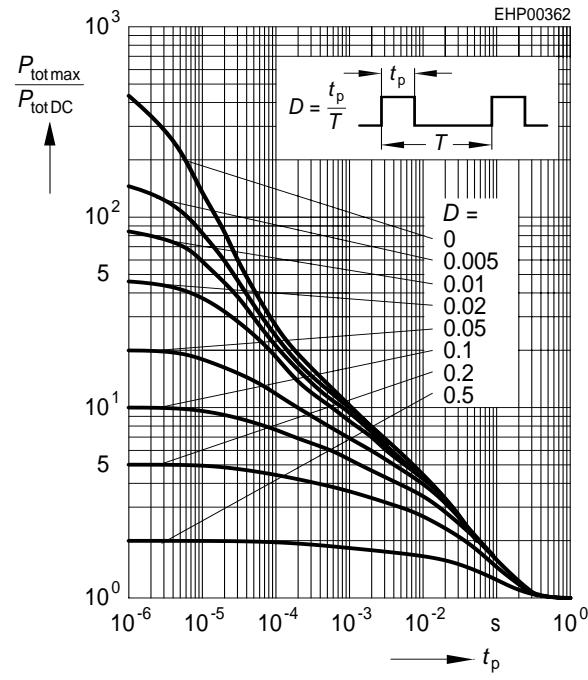


Total power dissipation $P_{\text{tot}} = f(T_S)$
BC847BL3/BC848BL3

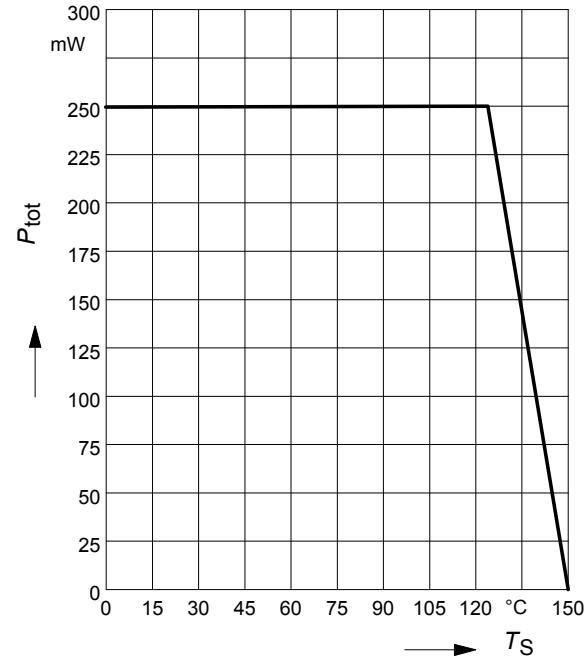


Permissible Pulse Load

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$
BC846/W-BC850/W

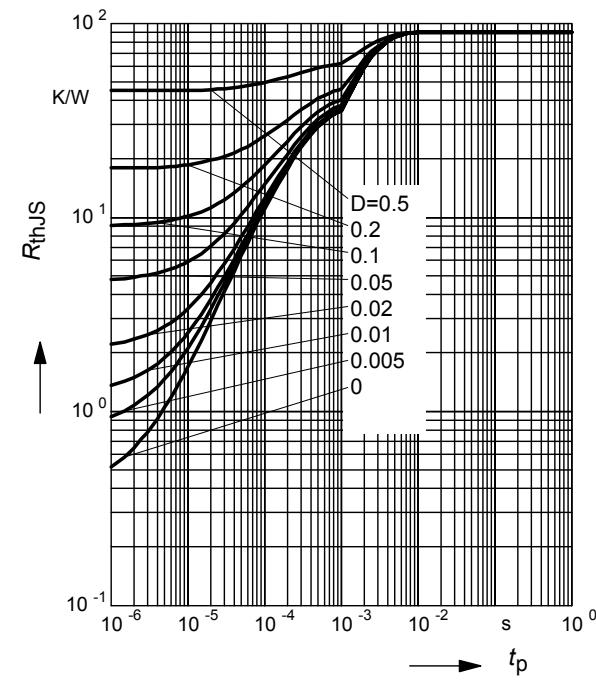


Total power dissipation $P_{\text{tot}} = f(T_S)$
BC846W-BC850W



Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

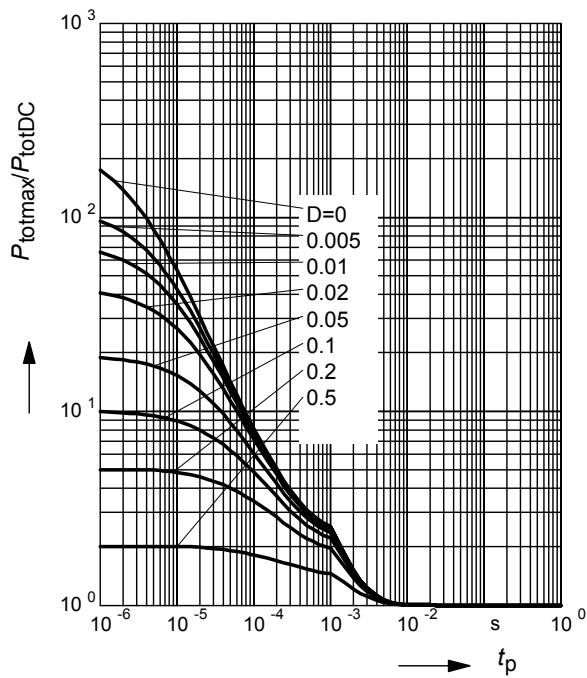
BC847BF



Permissible Pulse Load

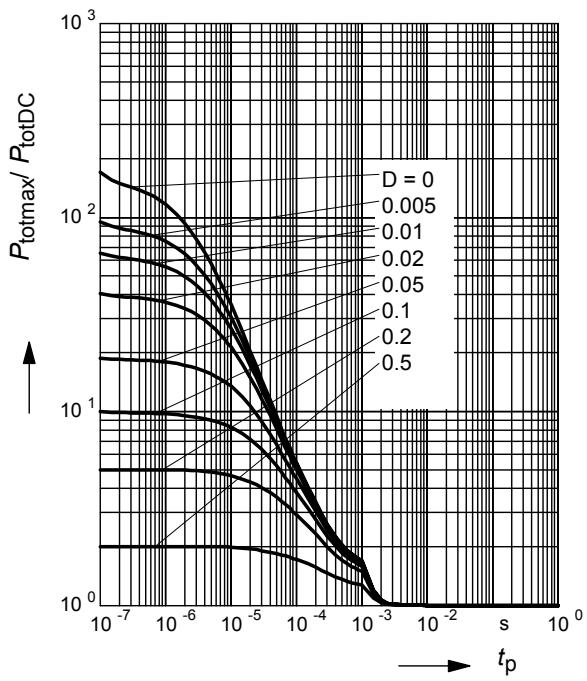
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BC847BF

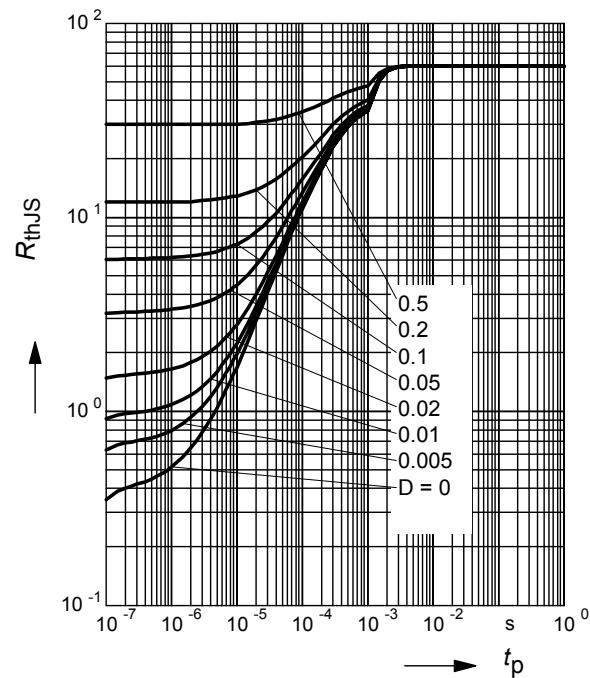
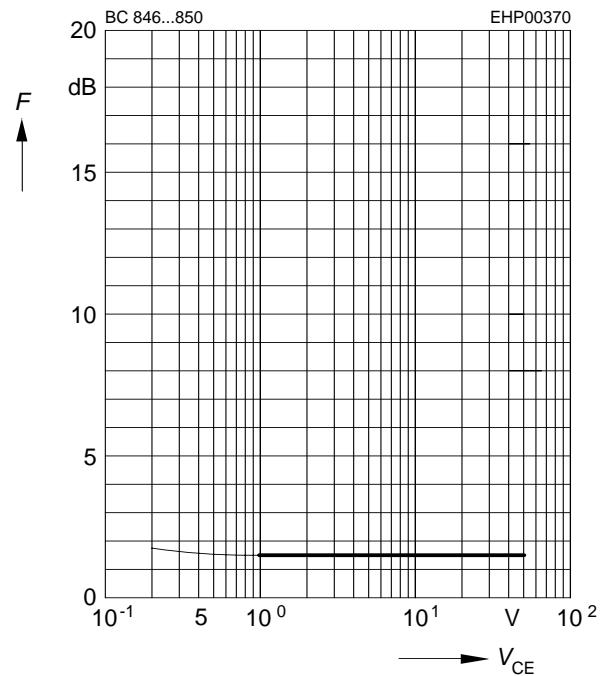

Permissible Pulse Load

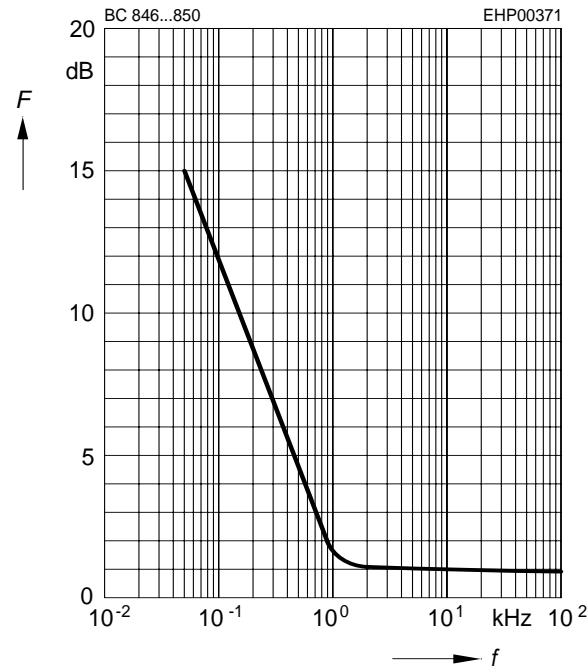
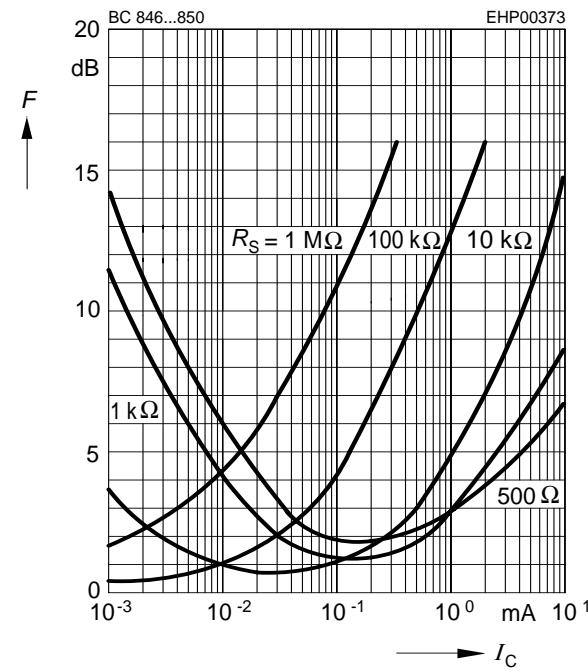
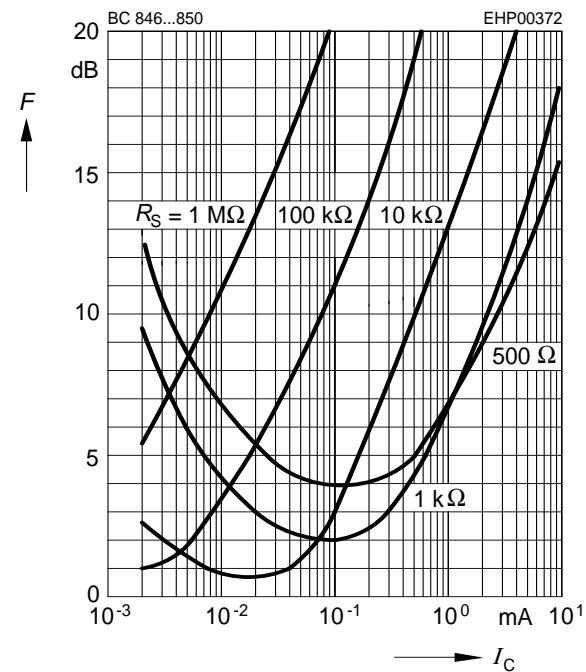
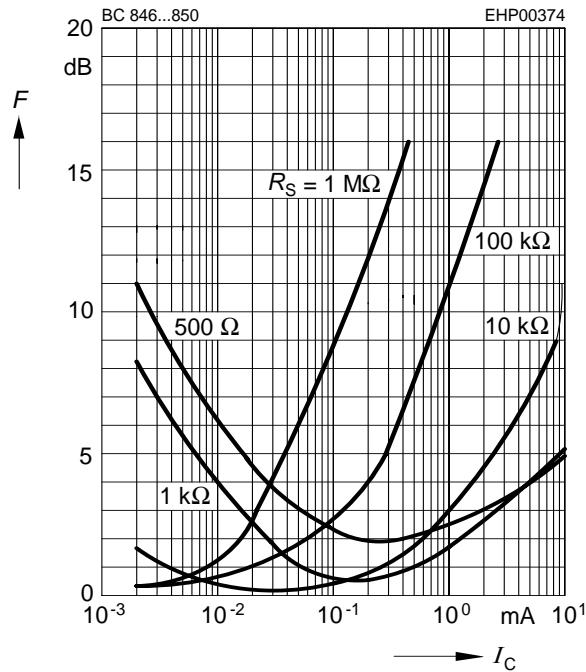
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BC847BL3, BC848BL3

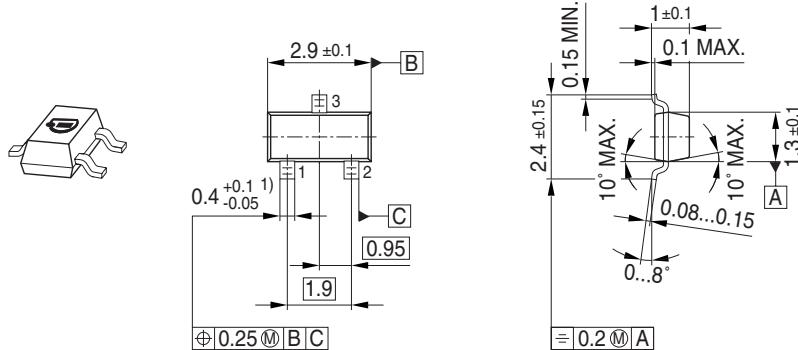

Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BC847BL3, BC848BL3


Noise figure $F = f(V_{\text{CE}})$
 $I_C = 0.2\text{mA}$, $R_S = 2\text{k}\Omega$, $f = 1\text{kHz}$


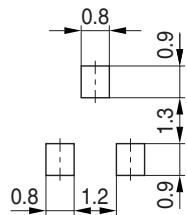
Noise figure $F = f(f)$
 $I_C = 0.2 \text{ mA}$, $V_{CE} = 5V$, $R_S = 2 \text{ k}\Omega$

Noise figure $F = f(I_C)$
 $V_{CE} = 5V$, $f = 1\text{kHz}$

Noise figure $F = f(I_C)$
 $V_{CE} = 5V$, $f = 120\text{Hz}$

Noise figure $F = f(I_C)$
 $V_{CE} = 5V$, $f = 10\text{kHz}$


Package Outline

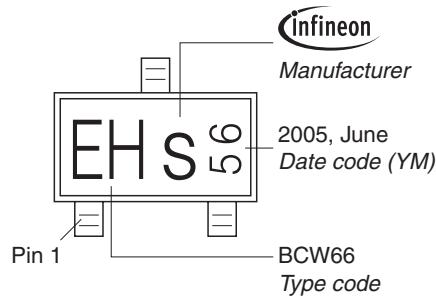


1) Lead width can be 0.6 max. in dambar area

Foot Print

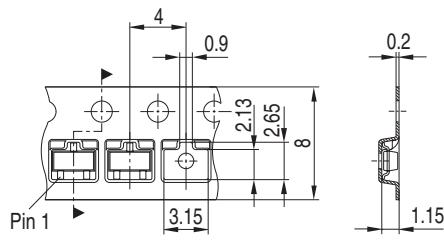


Marking Layout (Example)

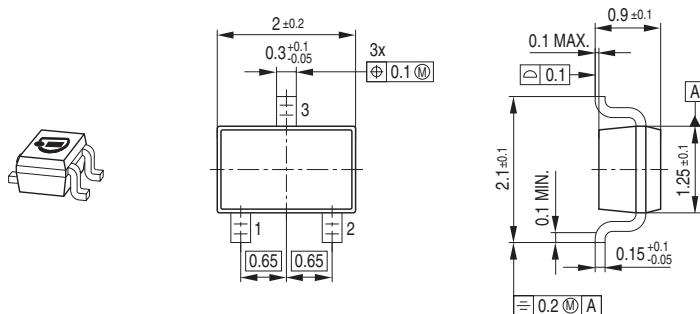


Standard Packing

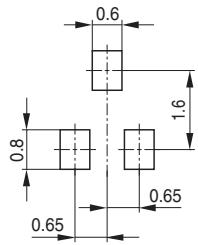
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



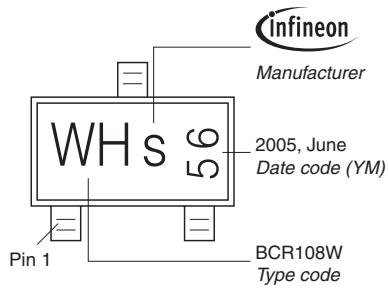
Package Outline



Foot Print

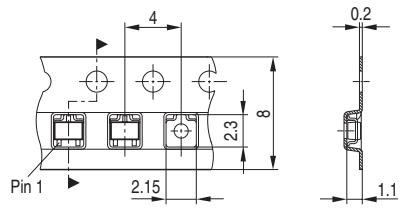


Marking Layout (Example)

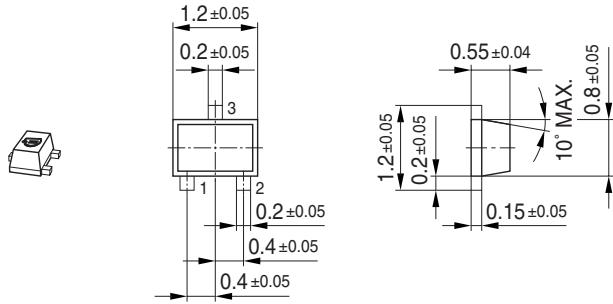


Standard Packing

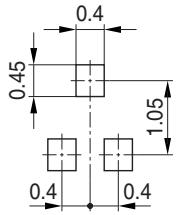
Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



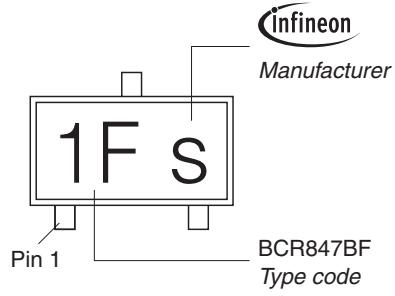
Package Outline



Foot Print

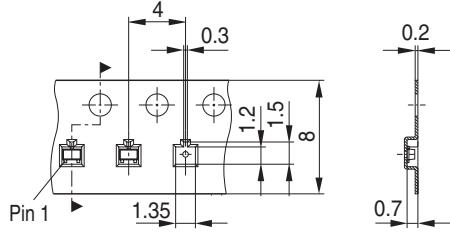


Marking Layout (Example)

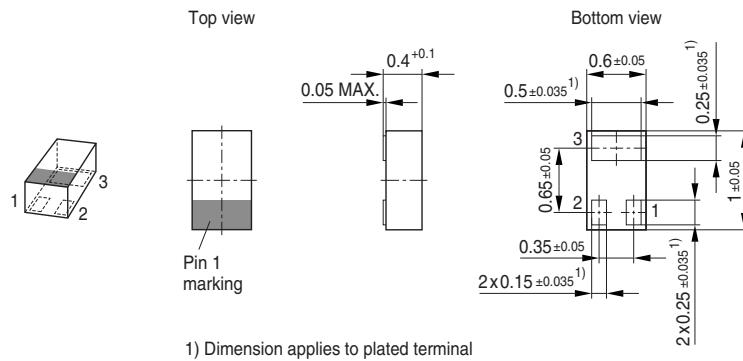


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel

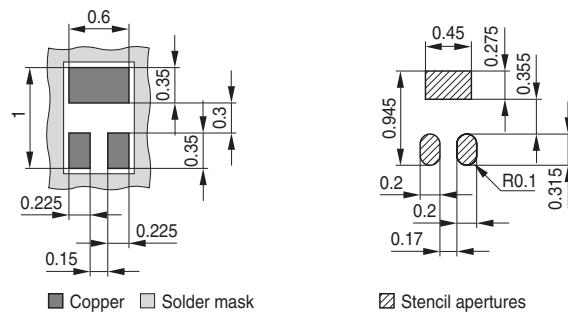


Package Outline

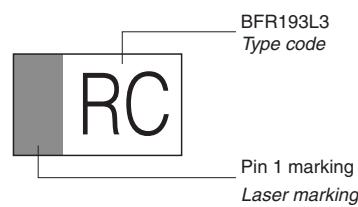


Foot Print

For board assembly information please refer to Infineon website "Packages"

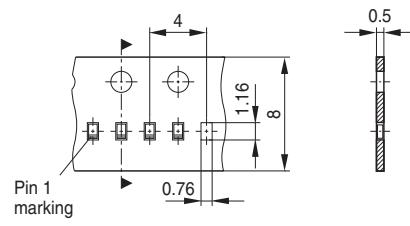


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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